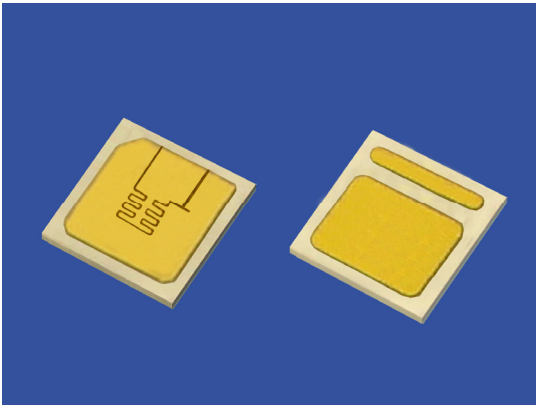


NEW!

Thick Copper Plated Alumina Substrate

Ceramic Solution for **High Power LED Flash**

Product



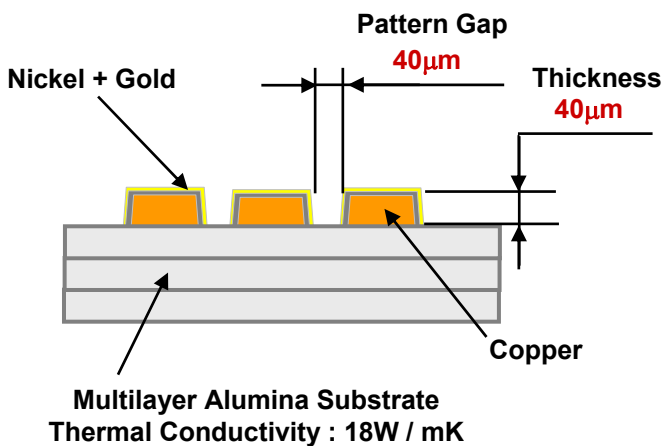
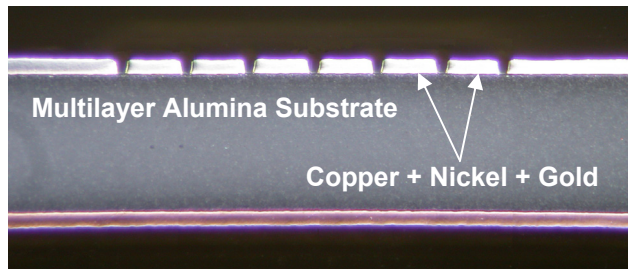
Features

- Alumina Thermal Conductivity : 18W / mK
- Thick Copper Plating to Improve Thermal Resistance
Copper Thickness : 40μm
- Fine Pattern for Flip Chip Mounting
Pattern Gap : 40μm
- Highly Reliable Plating Structure to Avoid Electromigration

Structure

Highly Reliable Plating Structure

Cross Section



Cross Section

